

Design Care

- 1 If possible, use SMD component instead of DIP component.
- 2 Keep all DIP components on same side (Top/Bottom).
- 3 The distance between 2 solder pads of 0402 components should be 0.26-0.45mm.
- 4 No silkscreen on VIA holes.
- 5 Mark the pole for polarity components.
- 6 Minimum trace/ vias /pads spacing.
The distance between any two chip components should be at least 1mm;
- 7 the distance between chip component and connector should be at least 5mm.
- 8 Keep clear around big IC (48pins or more) and BGA. 3.8mm is recommended.
- 9 The solder pad size (length/width) on PCB should be larger than pin size of component.
- 10 Temperature sensitive components (e.g. LED, battery) may be damaged in manual soldering process.
- 11 The distance between soldering points and neighbor SMD components should be at least 1mm.